

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. .... 10/340,126  
Priority Filing Date ..... January 10, 2003  
 Inventor ..... Zhongze Wang  
 Assignee ..... Micron Technology, Inc.  
Priority Group Art Unit ..... 2812  
Priority Examiner ..... Jennifer M. Kennedy  
 Attorney's Docket No. .... MI22-2457  
 Customer No. .... 021567  
 Title: Wafer Bonding Method of Forming Silicon-on-Insulator Comprising  
 Integrated Circuitry (as Amended)

**PRELIMINARY AMENDMENT**

To: Mail Stop Patent Application  
 Commissioner for Patents  
 P. O. Box 1450  
 Alexandria, VA 22313-1450

**VIA EXPRESS MAIL**

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Please enter the following amendments prior to examining the above-identified application.

**AMENDMENTS**

**Amendments to th Titl**

Please change the title to the following: -- WAFER BONDING  
METHOD OF FORMING SILICON-ON-INSULATOR COMPRISING  
INTEGRATED CIRCUITRY --.